



US00D404368S

# United States Patent [19]

Shimazu

[11] Patent Number: Des. 404,368

[45] Date of Patent: \*\*Jan. 19, 1999

[54] OUTER TUBE FOR USE IN A SEMICONDUCTOR WAFER HEAT PROCESSING APPARATUS

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[\*\*] Term: 14 Years

[21] Appl. No.: 82,978

[22] Filed: Feb. 2, 1998

### [30] Foreign Application Priority Data

Aug. 20, 1997 [JP] Japan ..... 9-65095

[51] LOC (6) Cl. .... 13-03

[52] U.S. Cl. .... D13/182

[58] Field of Search ..... D13/182; D15/144, D15/144.1, 199; 414/935-941, 217, 147; 437/247, 946

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### [57] CLAIM

I claim the ornamental design for an outertube for use in a semiconductor wafer heat processing apparatus, as shown and described.

### DESCRIPTION

FIG. 1 a perspective view of a outertube for use in a semiconductor wafer heat processing apparatus;  
FIG. 2 a front elevational view thereof;  
FIG. 3 a top plan view thereof;  
FIG. 4 a bottom plan view thereof; and,  
FIG. 5 a cross-sectional view taken along line V-V in FIG. 3 .

1 Claim, 2 Drawing Sheets

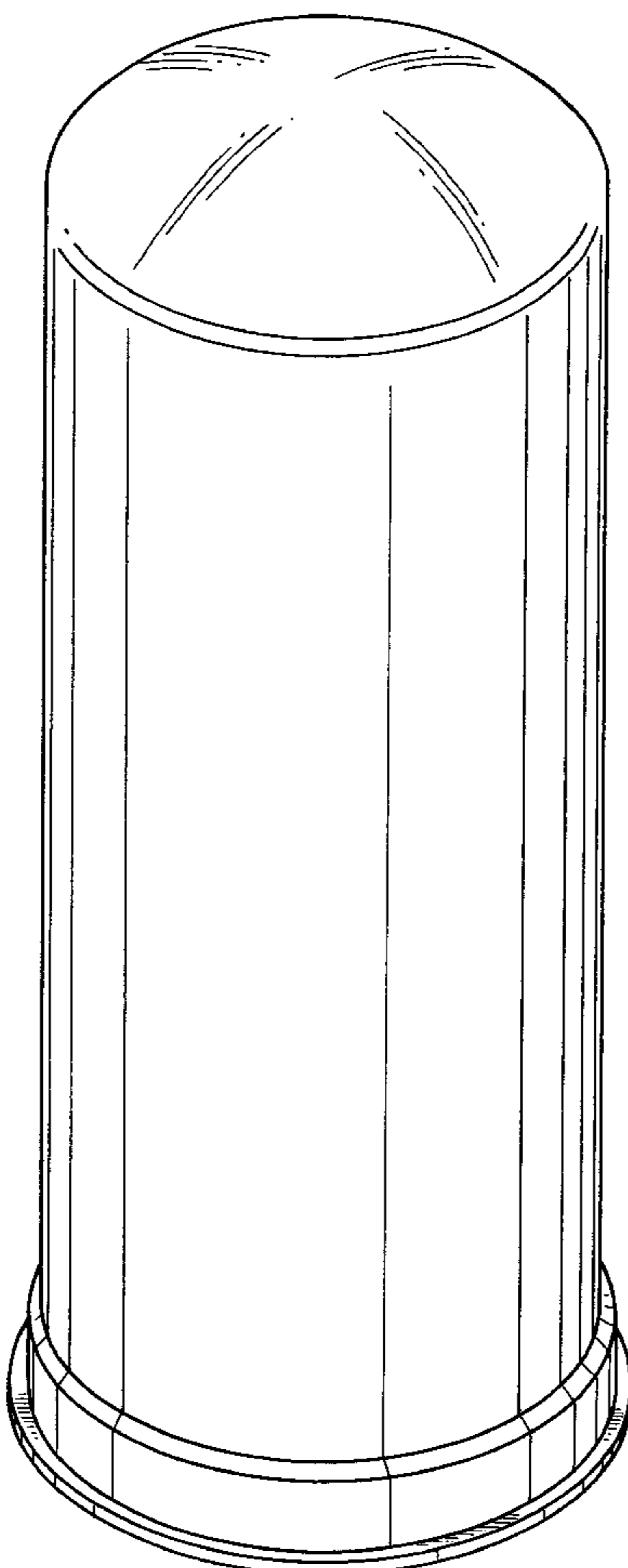


FIG. 1

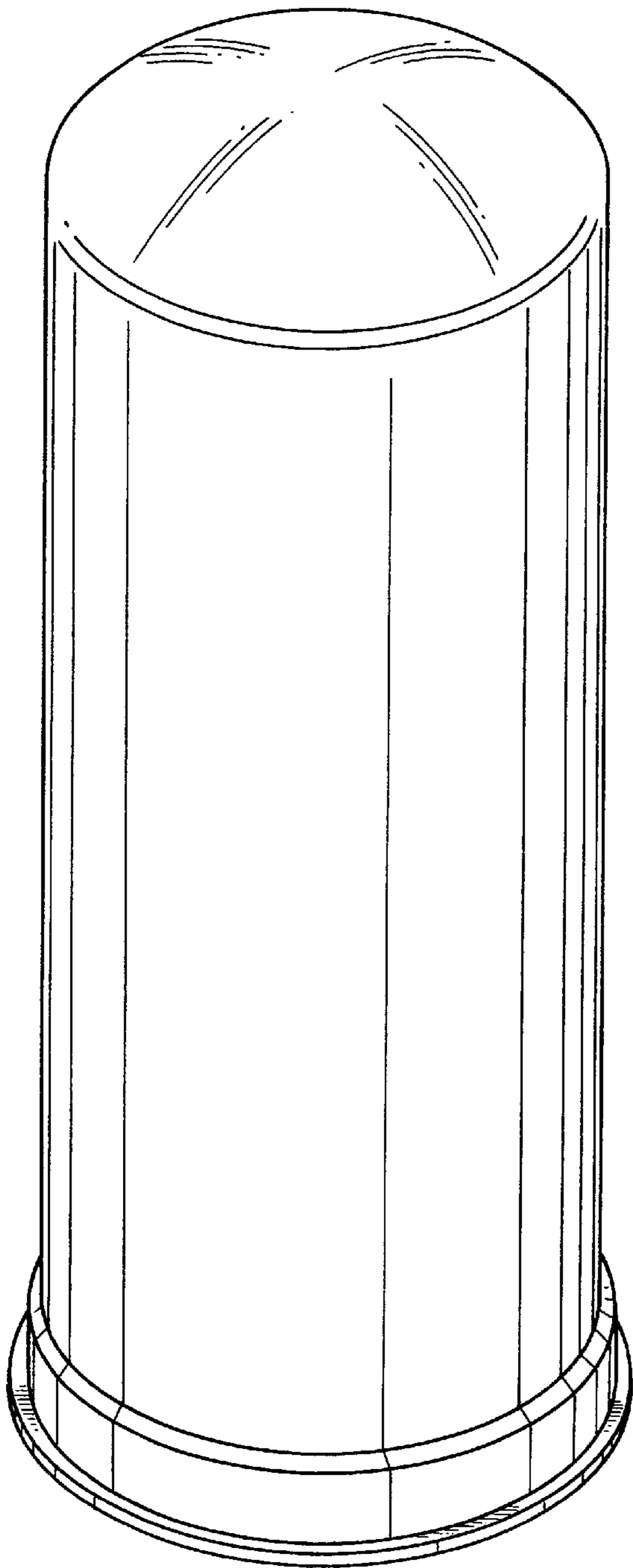


FIG. 2

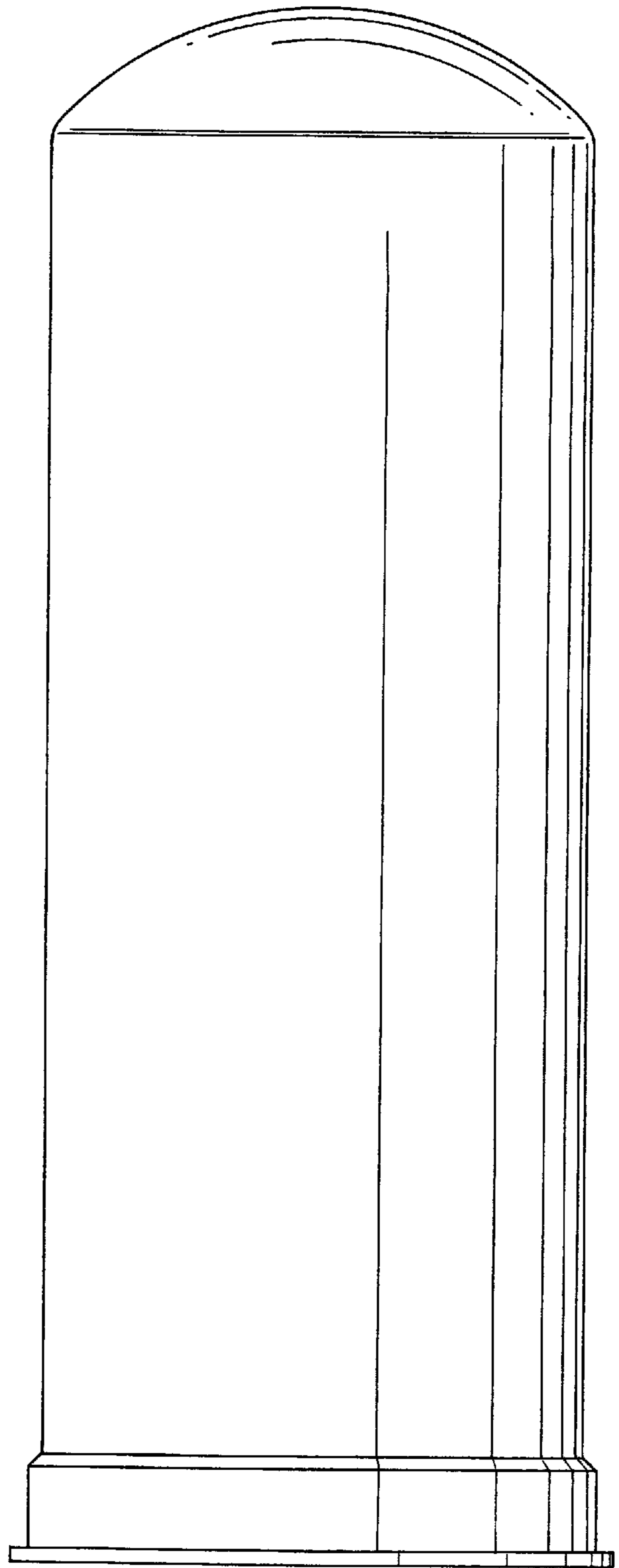


FIG. 3

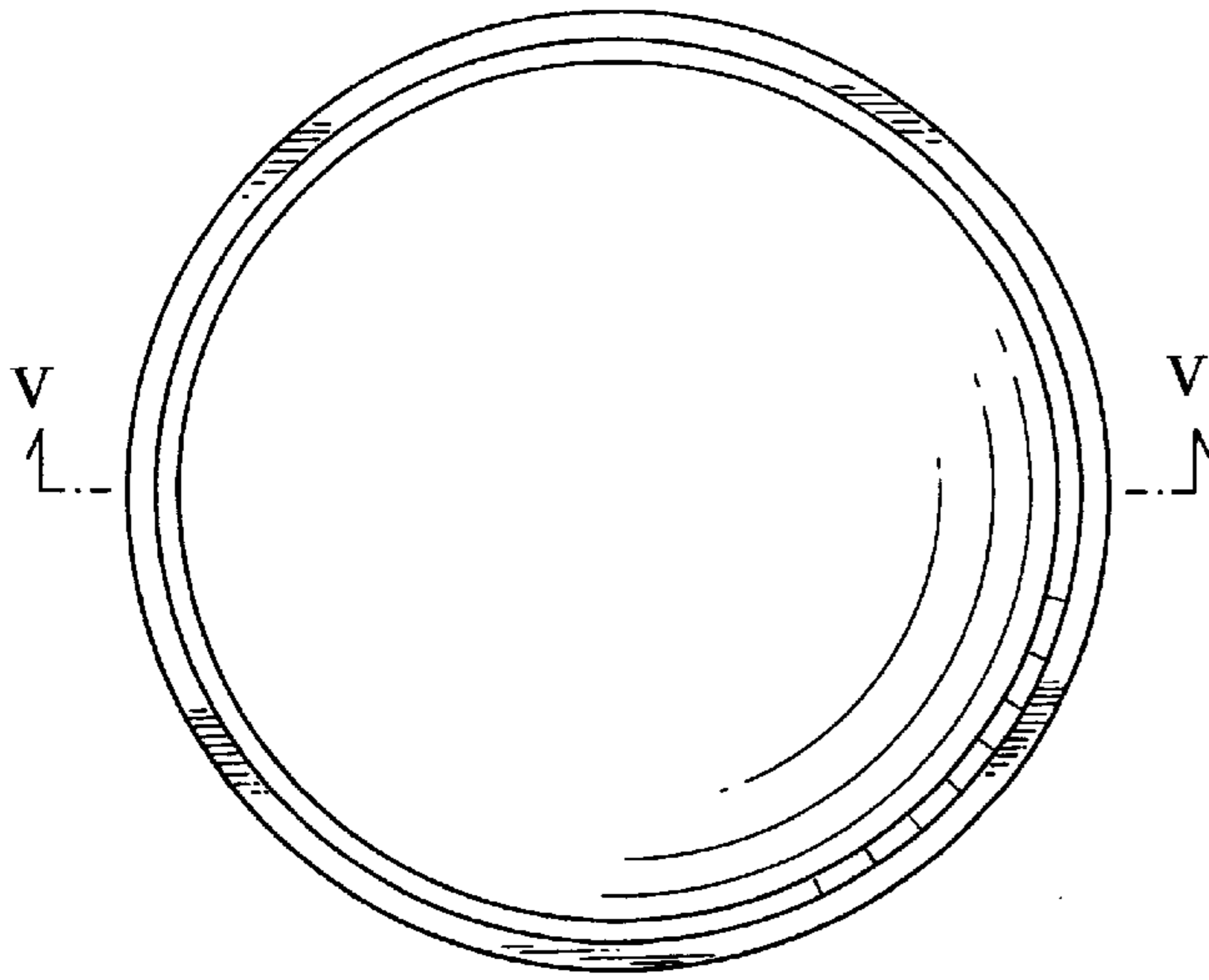


FIG. 4

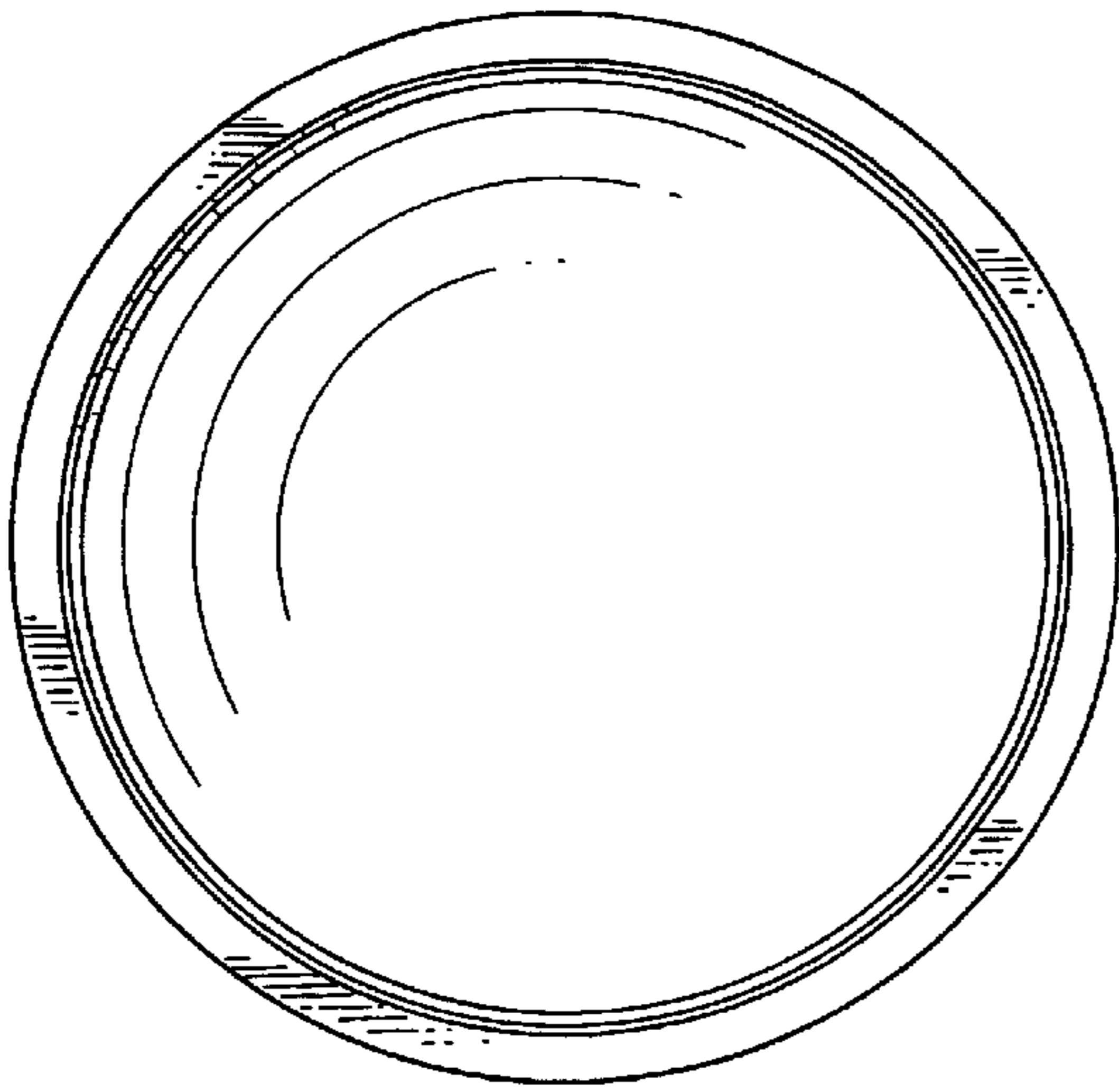


FIG. 5

